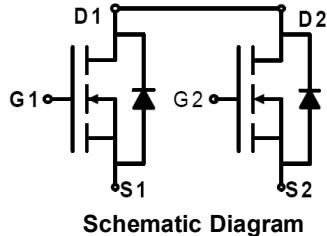


Dual N-Channel Trench Power MOSFET

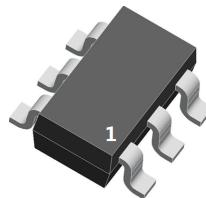
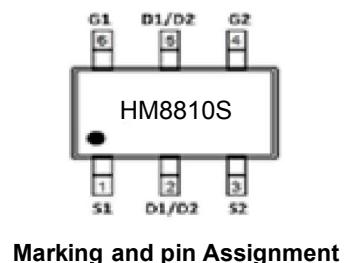
General Description

The HM8810S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching applications.



Features

- $V_{DS} = 20V, ID = 5A$
- $R_{DS(ON)} < 22m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)} < 28m\Omega @ V_{GS} = 2.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package



Application

- Battery protection
- Load switch
- Power management

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantit
HM8810S	HM8810S	SOT23-6	Ø180mm	8mm	3000 units

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	20	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 12	V
I_D	Drain Current-Continuous	5	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	25	A
P_D	Maximum Power Dissipation	1.5	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Table 2. Thermal Characteristic

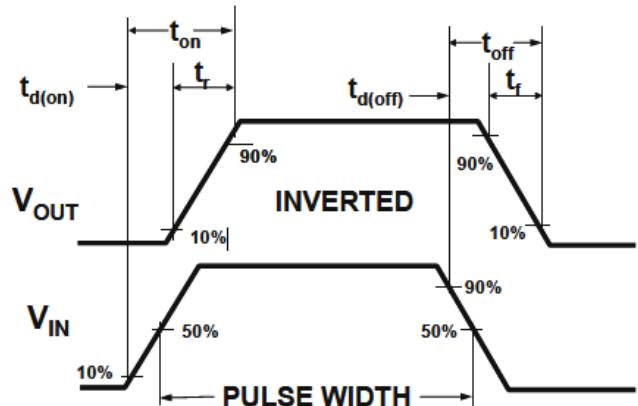
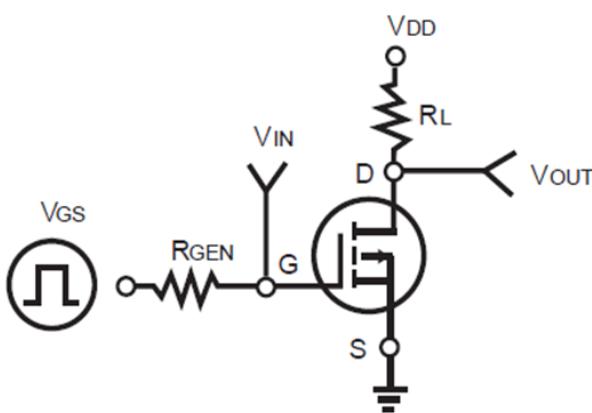
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	125	°C/W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	20	21.5		V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =19.5V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.45	0.65	1.0	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =5A	4	8		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =5A		18	22	mΩ
		V _{GS} =2.5V, I _D =4A		22.5	28	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =8V, V _{GS} =0V, f=1.0MHz		605		pF
C _{oss}	Output Capacitance			315		pF
C _{rss}	Reverse Transfer Capacitance			132		pF
Switching Times						
t _{d(on)}	Turn-on Delay Time	V _{DD} =10V, I _D =1A, V _{GS} =4.5V, R _G =6Ω		11		nS
t _r	Turn-on Rise Time			12		nS
t _{d(off)}	Turn-Off Delay Time			36		nS
t _f	Turn-Off Fall Time			32		nS
Q _g	Total Gate Charge	V _{DS} =10V, I _D =4A, V _{GS} =4.5V		10		nC
Q _{gs}	Gate-Source Charge			2.8		nC
Q _{gd}	Gate-Drain Charge			1.8		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current(Body Diode)				1.7	A
V _{SD}	Forward on Voltage ^(Note 1)	V _{GS} =0V, I _S =1.7A		0.79	1	V

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Switch Time Test Circuit and Switching Waveforms:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Power Dissipation

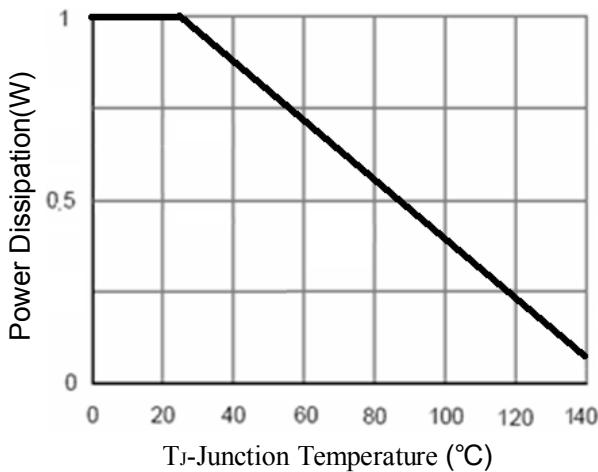


Figure2. Drain Current

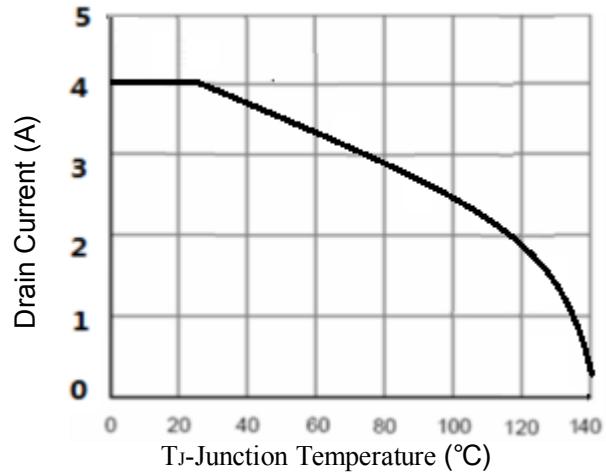


Figure3. Output Characteristics

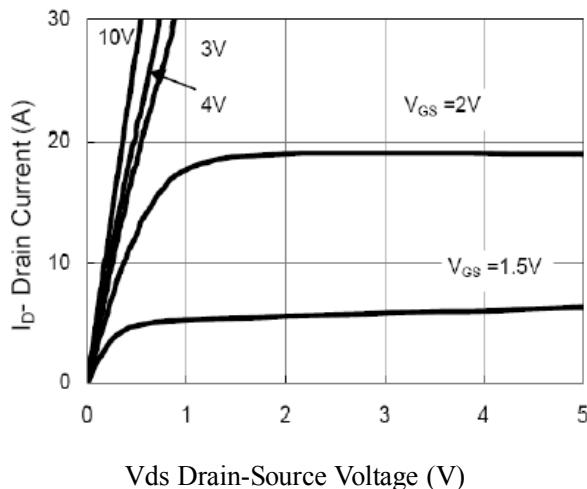


Figure4. Transfer Characteristics

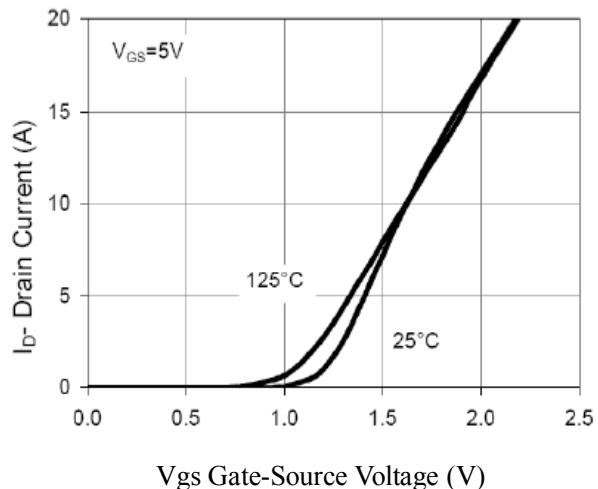


Figure5. Capacitance

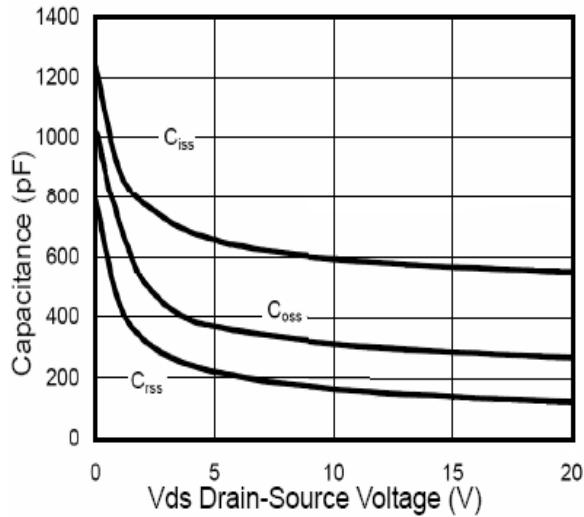


Figure6. $R_{DS(ON)}$ vs Junction Temperature

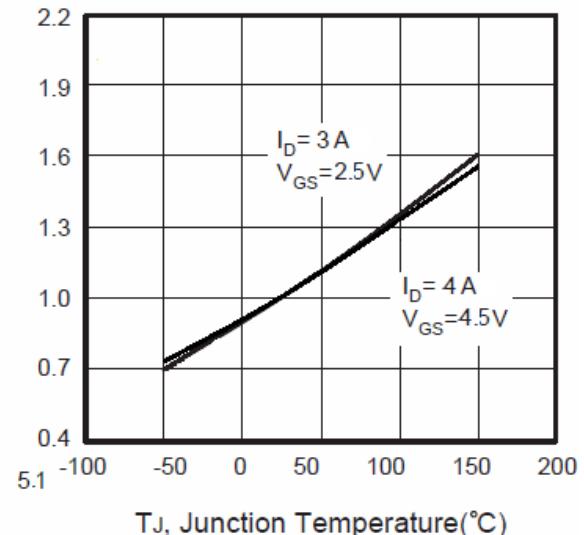


Figure7. Max BV_{DSS} vs Junction Temperature

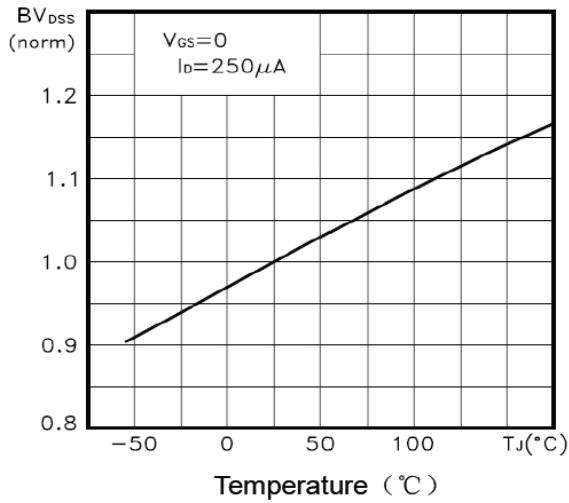


Figure8. $V_{GS(th)}$ vs Junction Temperature

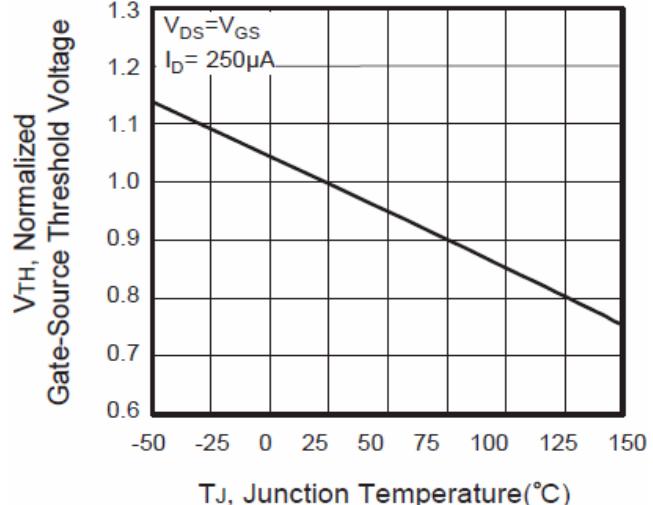


Figure9. Gate Charge Waveforms

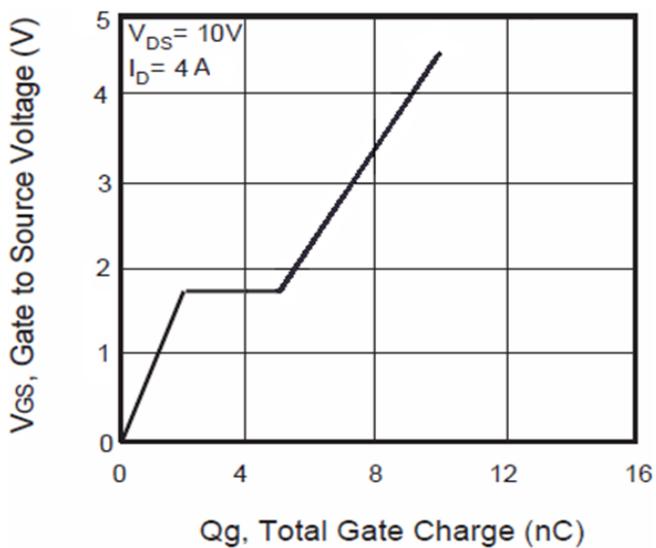


Figure10. Maximum Safe Operating Area

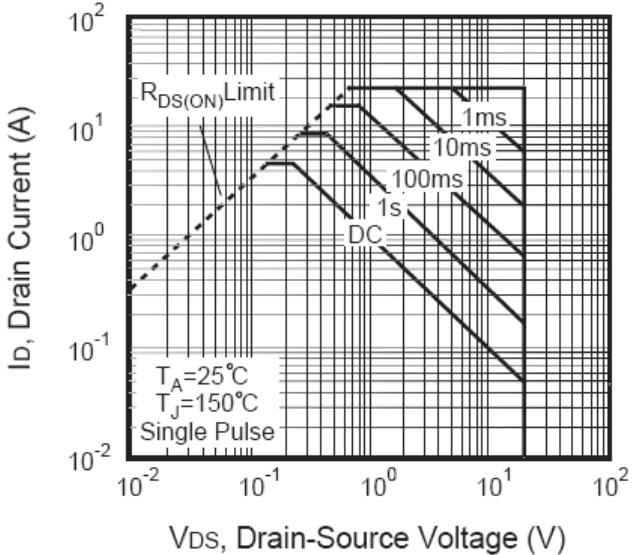
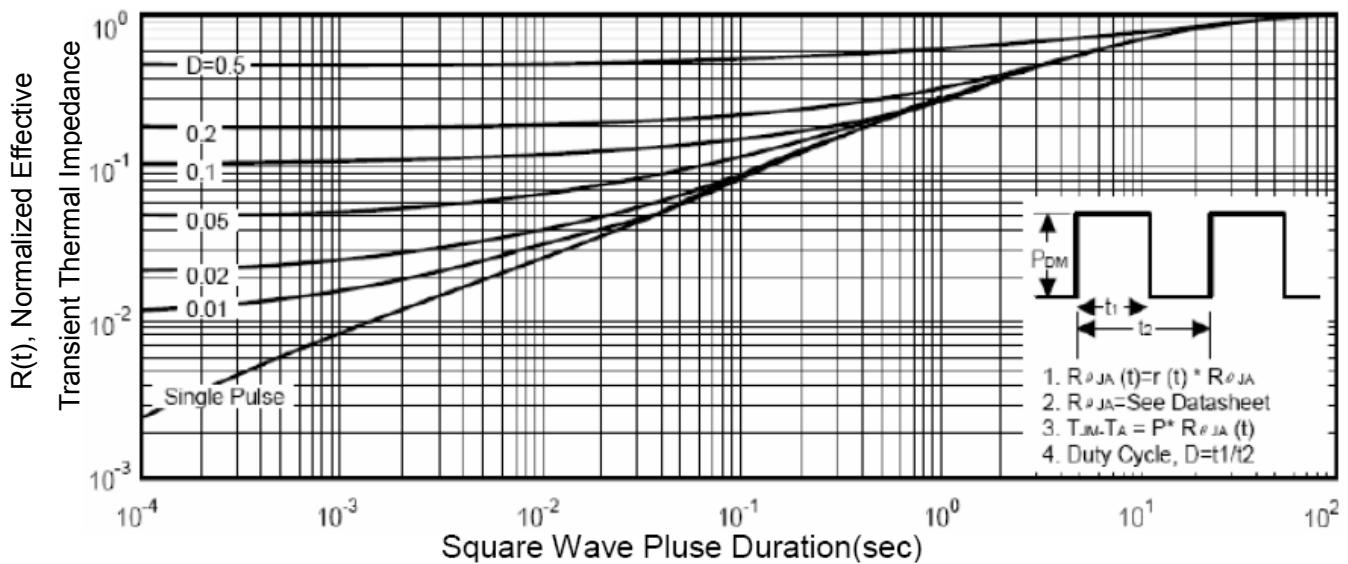
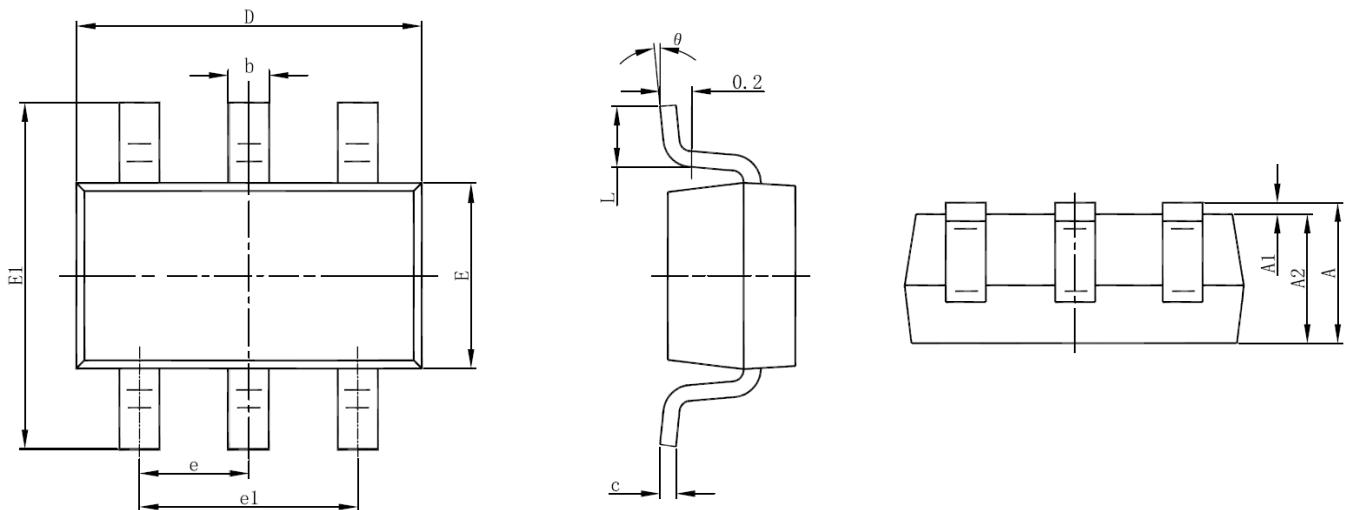


Figure11. Normalized Maximum Transient Thermal Impedance



SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°